

**PROCESS FOR PRODUCING SEMICONDUCTOR DEVICES, AND HEAT RESISTANT
ADHESIVE TAPE USED IN THIS PROCESS**

ABSTRACT OF THE DISCLOSURE

A process for producing semiconductor devices, comprising a mounting step of bonding semiconductor chips 15 onto die pads 11c of a metal lead frame 10 having, on its outer pad side, a heat resistant pressure-sensitive adhesive tape 20, a sealing step of sealing the semiconductor chip side of the lead frame with a sealing resin 17 to yield a sealed structure 21, and a cutting step of cutting the sealed structure 21 into the semiconductor devices 21a, which are individually separated, wherein the heat resistant adhesive tape 20 comprises a base layer and a pressure-sensitive adhesive layer containing a mold release agent. This process is a semiconductor device producing process wherein resin-leakage in the sealing step is appropriately prevented by the heat resistant adhesive tape while the stuck tape causes no troubles in any step after the sealing step.

(No Suitable Figure)